

# 400W, 3.4 - 3.6 GHz GaN Amplifier

Product datasheet

### **Description**

The HTH1D36P450H is an unmatched discrete GaN on SiC Power Amplifier with 400W saturated output power covering frequency range from 3.4 - 3.6 GHz.

#### **Features**

• Operating Frequency Range: 3.4 - 3.6 GHz

Operating Drain Voltage: +48V

Saturation Output Power: 400W

• Power Average: 55W

 Device can be used on a single-ended or in a push-pull configuration. Doherty application applicable

 Excellent thermal stability due to low thermal resistance package

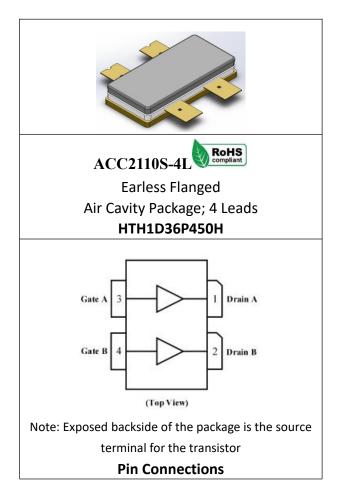
Enhanced robustness design without device degradation

• Efficiency: 48.7%@3.5GHz, WCDMA

• Gain: 14.6dB@3.5GHz, WCDMA

# **Applications**

- 3GPP 5G NR FR1 n48/77/78
- 4G-LTE B42
- Amplifier for Micro and Macro Base Stations
- Repeaters/DAS
- Mobile Infrastructure



#### **Ordering Information**

Part Number	Description
HTH1D36P450H	Reel Package
HTH1D36P450HEVB	3.4 - 3.6 GHz EVB



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#### **RF Characteristics (WCDMA)**

Freq (GHz)	Gain (dB)	Eff (%)	ACPR_L* @5MHz (dBc)	ACPR_U* @5MHz (dBc)
3.4025	14.1	48.44	-24.6	-24.4
3.5000	14.6	48.69	-26.6	-26.6
3.5975	14.4	49.09	-28.2	-28.2

Test conditions unless otherwise noted: 25 °C, VVDD = +48Vdc, IDQ\_Carrier= 240mA, Vgsp = -5.3V, PAVG = 47.4 dBm 1C-WCDMA 5MHz Signal, 9.9 dB PAR @ 0.01% CCDF test on WATECH Application Board

# **Absolute Maximum Ratings**

Parameter	Range/Value	Unit
Drain voltage (VDSS)	+150	V
Gate voltage (V <sub>GS</sub> )	-10 to +2.0	V
Storage Temperature (Tstg)	-65 to +150	°C
Junction Temperature (T <sub>J</sub> )	225	°C

# **Electrical Specification**

#### **DC Characteristics (Carrier)**

Parameter	Conditions	Min	Тур	Max	Unit
Breakdown Voltage V(BR)DSS	Vgs=-8V, Ids=24mA	150	-	-	V
Gate-Source Threshold Voltage V <sub>GS(th)</sub>	Vds=10V, lds=24mA	-3.6	-2.8	-2.2	V
Drain Leakage Current IDSS	Vgs=-8V, Vds=50V	-	7.2	-	mA
Gate Leakage Current Igss	Vgs=-10V, Vds=0V	-	-2.4	-	mA

#### **DC Characteristics (Peak)**

Parameter	Conditions	Min	Тур	Max	Unit
Breakdown Voltage V(BR)DSS	Vgs=-8V, Ids=33.6mA	150	-	-	V
Gate-Source Threshold	\/ds=10\/  ds=22.6mA	2.6	2.0	2.2	V
Voltage V <sub>GS(th)</sub>	Vds=10V, Ids=33.6mA	-3.6	-2.8	-2.2	V
Drain Leakage Current Ibss	Vgs=-8V, Vds=50V	-	10	-	mA
Gate Leakage Current Igss	Vgs=-10V, Vds=0V	-	-3.6	-	mA

<sup>\*</sup>Uncorrected DPD



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#### **RF Characteristics (Pulsed CW)**

Parameter	Freq (GHz)	Min	Тур.	Max	Unit
P1dB	3.5	-	50.6	-	dBm
P5dB	3.5	50	55.8	57	dBm
Gain Flatness	3.4 - 3.6 PAVG = 47.4 dBm	-	0.5	-	dB

Test conditions unless otherwise noted: 25 °C, VDD = +28Vdc,  $IDQ\_Carrier = 300mA$ , Vgsp = -5.3V,  $Pulse\ Width = 1ms$ ,  $Duty\ Cycle = 10\%\ test\ on\ WATECH\ Production\ Board$ 

#### **RF Characteristics (WCDMA)**

Parameter	Conditions	Min	Тур.	Max	Unit
Frequency		3.5			GHz
Gain	PAVG = 47.4 dBm	10	14.6	20	dB
Eff	PAVG = 47.4 dBm	33	48.7	70	%
ACPR@5MHz*	PAVG = 47.4 dBm	-40	-26.6	-20	dBc

Test conditions unless otherwise noted: 25 °C, VVDD = +48Vdc, IDQ\_Carrier= 240mA, Vgsp = -5.3V, 1C-WCDMA 5MHz Signal, 9.9 dB PAR @ 0.01% CCDF test on WATECH Application Board

#### **Load Mismatch Test**

Condition	Test Result
VSWR=10:1, at all Phase Angles, VDD = +48Vdc, IDQ_Carrier= 240mA,	No Device
1C-WCDMA 5MHz Signal, 9.9 dB PAR, PAVG = 47.4 dBm, Frequency 3.4 - 3.6	
GHz, test on WATECH Application Board	Degradation

#### **Thermal Information**

Parameter	Condition	Value (Typ)	Unit
Thermal Resistance Junction to Case (Rтн)	Tcase= 80°C, VDD = +48Vdc,		
	IDQ_Carrier= 240mA, 1C-WCDMA 5MHz	0.88	°C /W
	Signal, 9.9 dB PAR, PAVG = 47.4 dBm		

<sup>\*</sup>Uncorrected DPD, ACPR measured in 3.84MHz Channel Bandwidth @± 5MHz Offset



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#### **Load Pull Performance Carrier**

Test conditions unless otherwise noted: 25 °C, VDD = +48Vdc, IDQ= 200mA, PW = 40us, DC= 4%

	Max Output Power (Carrier)						
Freq Z_source Z_load [1] Gain P3dB P3dB Eff						Eff	
(GHz)	(Ω)	(Ω)	(dB)	(dBm)	(W)	(%)	
3.4	8.34-j*23.84	11.4-j*2.98	17.6	54.04	254	52.1	
3.6	22.66-j*24.66	10.6+j*0.06	18.1	54.18	262	52.3	

#### [1] Load impedance for optimum P3dB pout

	Max Drain Efficiency (Carrier)						
Freq Z_source Z_load [2] Gain P3dB P3dB Eff						Eff	
(GHz)	(Ω)	(Ω)	(dB)	(dBm)	(W)	(%)	
3.4	8.34-j*23.84	9.69-j*14.48	18.8	52.1	162	71.3	
3.6	22.66-j*24.66	16.56-j*10.32	19.6	52.3	170	71.8	

<sup>[2]</sup> Load impedance for optimum P3dB efficiency



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#### **Load Pull Performance Peak**

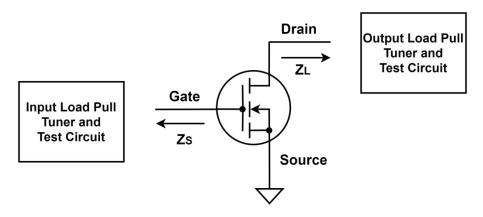
Test conditions unless otherwise noted: 25 °C, VDD = +48Vdc, IDQ= 300mA, PW = 40us, DC= 4%

	Max Output Power (Peak)						
Freq Z_source Z_load [1] Gain P3dB P3dB E1						Eff	
(GHz)	(Ω)	(Ω)	(dB)	(dBm)	(W)	(%)	
3.4	8.21-j*21.17	13.38-j*6.45	17.4	55.6	363	63.2	
3.6	21.51-j*17.67	14.39-j*0.08	17.3	55.6	363	58.7	

[1] Load impedance for optimum P3dB pout

Max Drain Efficiency (Peak)						
Freq	Z_source Z_load [2] Gain				P3dB	Eff
(GHz)	(Ω)	(Ω)	(dB)	(dBm)	(W)	(%)
3.4	8.21-j*21.17	9.33-j*12.89	18.7	54.6	288	69.8
3.6	21.51-j*17.67	14.79-j*10.75	19.3	54.4	275	68.3

[2] Load impedance for optimum P3dB efficiency



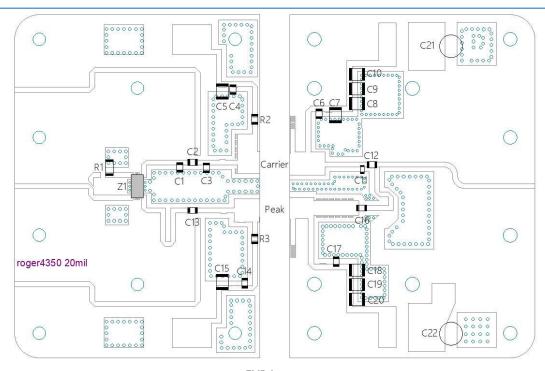
 $Z_source:$  Measured impedance presented to the input of the device at the package reference plane  $Z_source:$  Measured impedance presented to the output of the device at the package reference plane



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# HTH1D36P450H 3.4 - 3.6 GHz Reference Design



**EVB Layout** 

# Bill of Materials (BoM) - HTH1D36P450H

## 3.4 - 3.6 GHz Reference Design

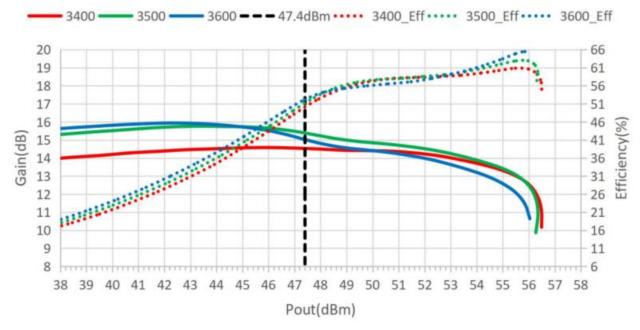
Reference	Value	Description	Manufacturer	P/N
01		400W, 3.4 - 3.6 GHz Watech		HTH1D36P450H
Q1	_	GaN on SiC PA	vvatecii	H1H1D30F430H
C1	0p3F	MLCC	Murata	GQM2195G2ER30BB12
C3	0p7F	MLCC	Murata	GQM2195G2ER70BB12
C2, C13, C17	16pF	MLCC	Murata	GQM2195C2E160JB12
C4, C12, C14	4p7F	MLCC	Murata	GQM2195G2E4R7BB12
C16	6p8F	MLCC	Murata	GQM2195G2E6R8BB12
C11	0p1F	MLCC	Murata	GQM1875C2ER10BB12
C16	3pF	MLCC	Murata	GQM2195G2E3R0BB12
C5, C7, C8, C9, C10 C15, C18, C19, C20	10uF /100V	MLCC	Murata	GRM32EC72A106KE05L



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Reference	Value	Description	Manufacturer	P/N
C21, C22	220uF/ 100V	Electrolytic Capacitor	Vishay	MAL213669221E3
R1	51Ω	High Frequency/RF Resistors	ANAREN	C8A50Z4B
R1, R3	20Ω	Thick Film Resistor	YAGEO	RC0603FR-0720RL
Z1	-	Hybrid Coupler 3dB, 90° ANAREN X3C35F1-03S		X3C35F1-03S
PCB	Rogers 4350B (er = 3.66), 20 mil (0.508 mm), 35 μm (1oz)			

#### **Performance Plots**



Pulsed CW, Gain and Efficiency vs Pout

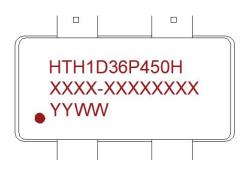
Test conditions unless otherwise noted: 25 °C, VDD = +48Vdc, IDQ= 350mA, Vgsp = -5.7V, PW = 100us, DC= 10% test on WATECH Application Board



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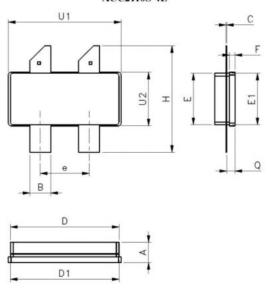
#### **Package Marking and Dimensions**



- Line1 (fixed): Device name in W/O
- Line2 (unfixed): Marking Lot No in W/O (Sample: E596-EERA0001)
- Line3 (unfixed): Date Code
  This Marking SPEC only stipulates the
  content of Marking. For marking
  requirements such as font and size, please
  refer to the latest version of "Watech
  Product Printing Specification"

#### Marking

ACC2110S-4L



Symbol	Dimensions in Millimeters			Dimensions in Inches		
	Min.	Mon.	Max.	Min.	Mon.	Max.
Α	3.55	3.71	3.86	0.140	0.146	0.152
В	3.68	3.81	3.94	0.145	0.150	0.155
С	0.04	0.11	0.18	0.002	0.004	0.007
D	19.61	19.81	20.01	0.772	0.780	0.788
DI	19.61	19.81	20.01	0.772	0.780	0.788
E	9.28	9.40	9.52	0.365	0.370	0.375
El	9.28	9.40	9.52	0.365	0.370	0.375
e	*	8.89	-	-	0.35	
F	0.95	1.02	1.09	0.037	0.040	0.043
Н	18.93	19.43	19.93	0.745	0.765	0.785
HI	12.57	12.70	12.83	0.495	0.500	0.505
L	4.71	4.83	4.95	0.185	0.190	0.195
Q	1.43	1.53	1.63	0.056	0.060	0.064
UI	20.51	20.58	20.65	0.807	0.810	0.813
U2	9.71	9.78	9.85	0.382	0.385	0.388

**Package Dimensions** 

# WATECH

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# **Handling Precautions**

Parameter	Grade	
Moisture Sensitivity Level MSL	3	

Parameter	Rating	Standard	
ESD – Human Body Model (HBM)	Class 1B	JESD22-A114	
ESD – Human Body Model (MM)	Class A	EIA/JESD22-A115	
ESD – Charged Device Model (CDM)	Class III	JESD22-C101	



#### **RoHS Compliance**

This product is compliant with the 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment), as amended by Directive 2015/863/EU.

#### **Datasheet Status**

Document status	Product status	Definition
Objective Datasheet Design simulation		Product objective specification
Preliminary Datasheet Customer sample		Engineering samples and first test results
Product Datasheet Mass production		Final product specification

#### **Abbreviations**

Acronym	Definition	
GaN on SiC	Gallium Nitride on Silicon Carbide	
CW	Continuous Waveform	



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# **Revision history**

Document ID	Datasheet Status	Release Date	Revision Version
Rev 1.1	Preliminary	Febr. 2021	Preliminary
Rev 1.2	Preliminary	Sept. 2021	Demo EVB upgrade
Rev 1.3	3 Product March 2023		New format based on English
VEA 1.2	Product	IVIAICII 2025	version datasheet



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For the latest specifications, additional product information, worldwide sales and distribution locations and information about WATECH:

• Web: <u>www.watechelectronics.com</u>

Email: MKT@huatai-elec.com

For technical questions and application information:

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